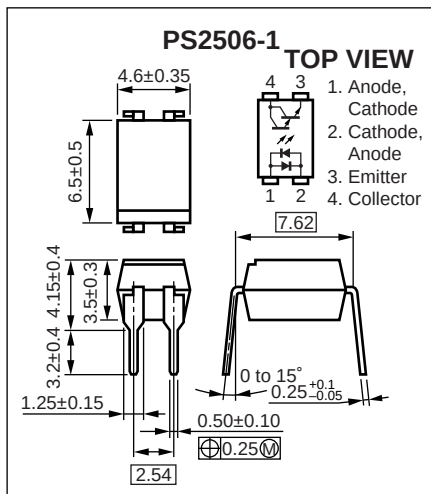


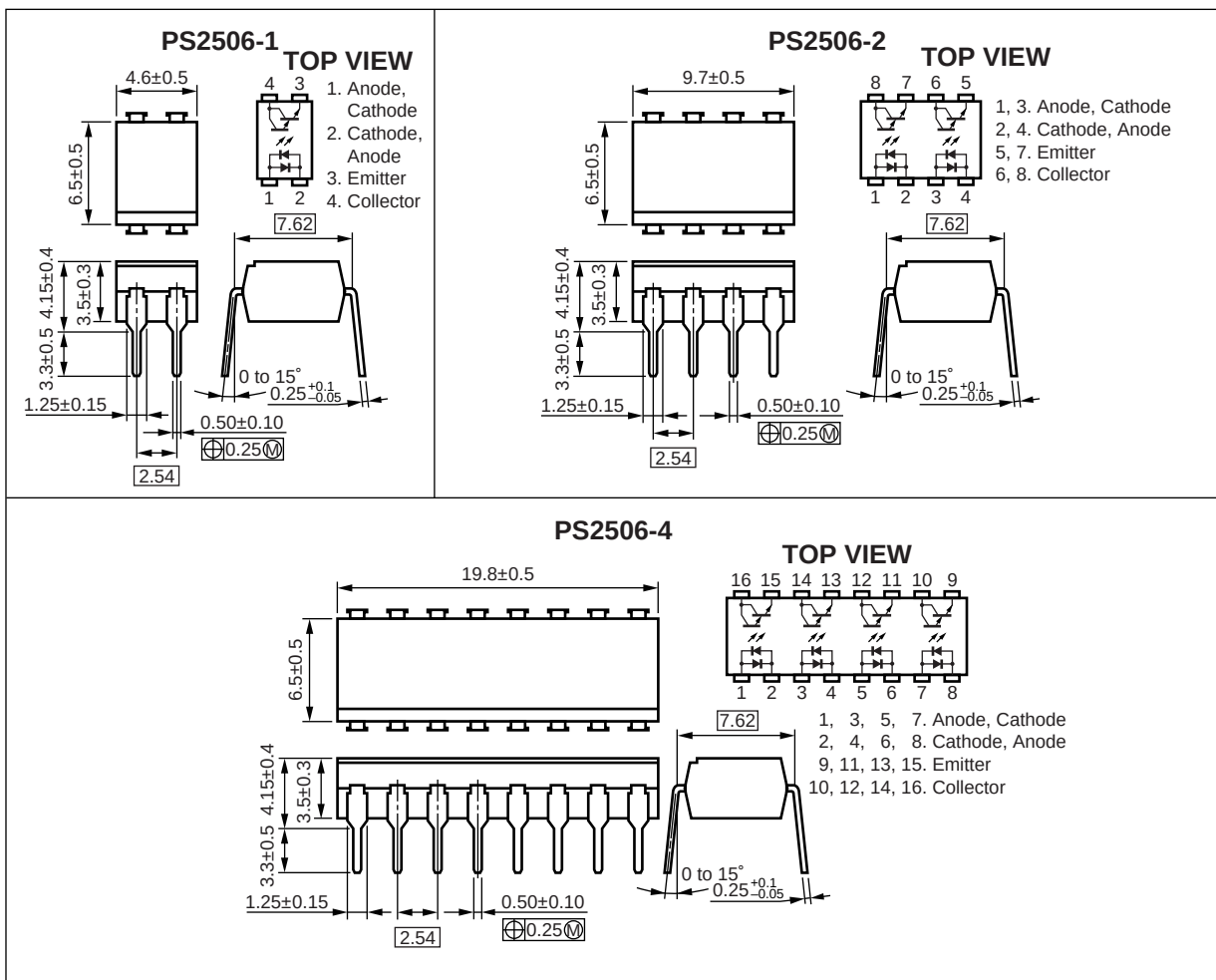
PACKAGE DIMENSIONS (UNIT : mm)

DIP Type (New package)

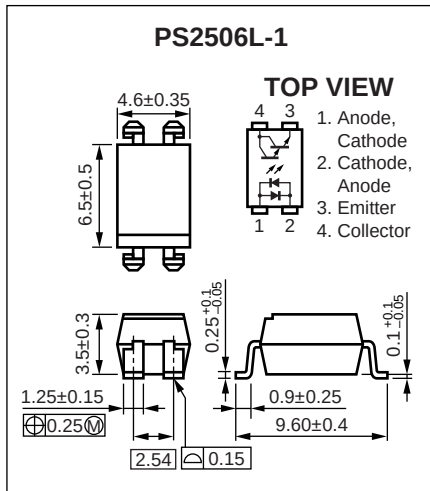


Caution New package 1-ch only

DIP Type

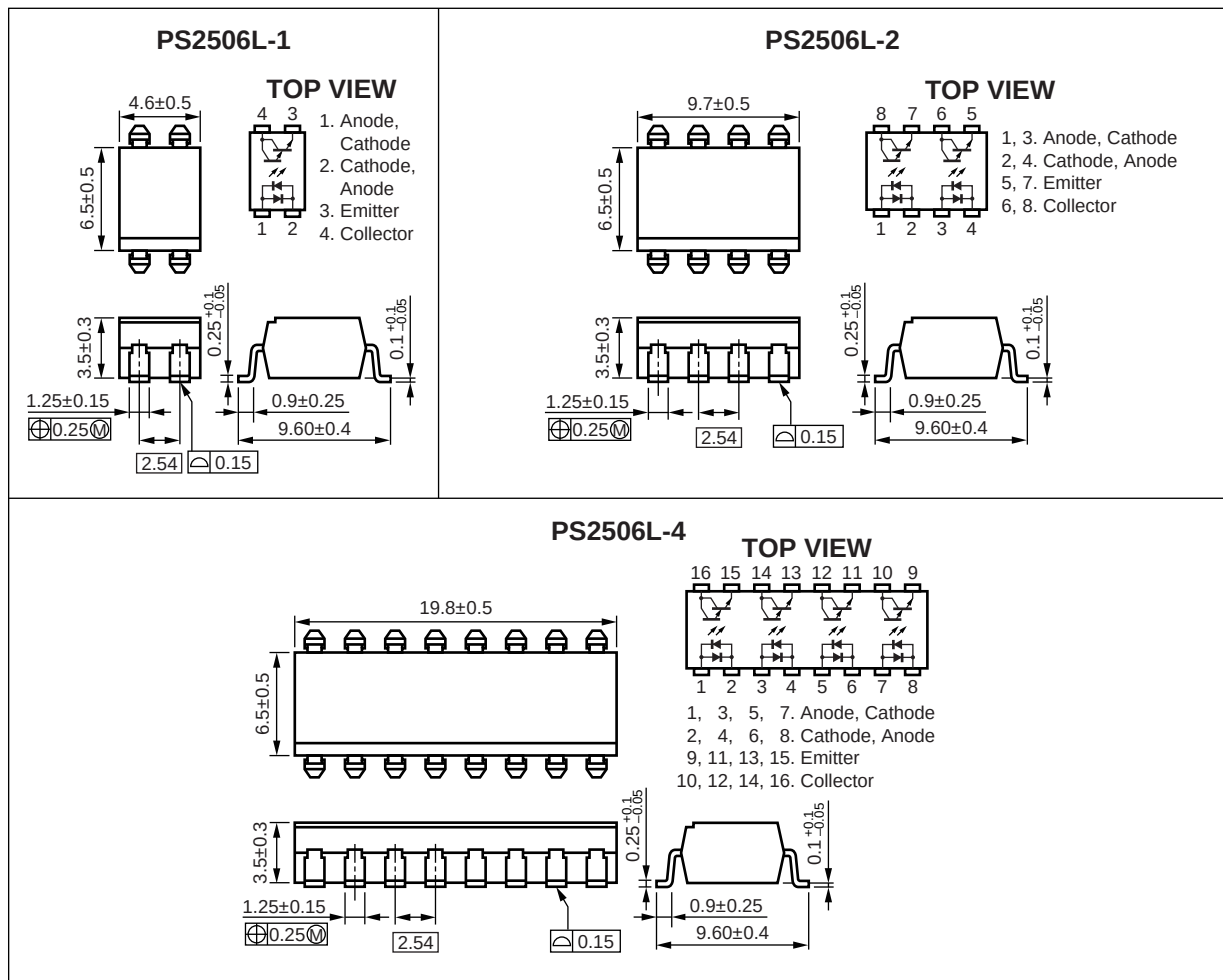


Lead Bending Type (New package)

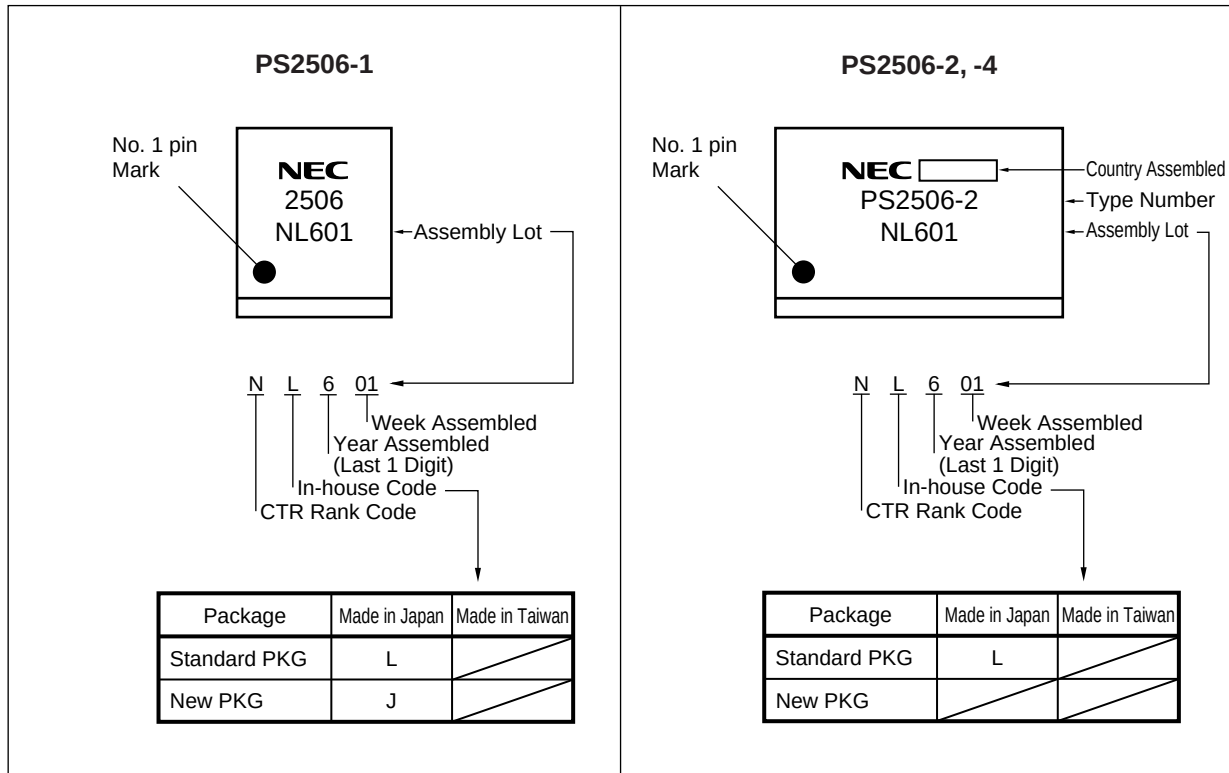


Caution New package 1-ch only

Lead Bending Type



★ MARKING EXAMPLE



★ ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number ^{*1}
PS2506-1	PS2506-1-A	Pb-Free	Magazine case 100 pcs	Standard products (UL Approved)	PS2506-1
PS2506L-1	PS2506L-1-A				
PS2506L-1-E3	PS2506L-1-E3-A		Embossed Tape 1 000 pcs/reel		
PS2506L-1-E4	PS2506L-1-E4-A				
PS2506L-1-F3	PS2506L-1-F3-A		Embossed Tape 2 000 pcs/reel		
PS2506L-1-F4	PS2506L-1-F4-A				
PS2506-2	PS2506-2-A		Magazine case 45 pcs		PS2506-2
PS2506L-2	PS2506L-2-A				
PS2506L-2-E3	PS2506L-2-E3-A		Embossed Tape 1 000 pcs/reel		
PS2506L-2-E4	PS2506L-2-E4-A				
PS2506-4	PS2506-4-A		Magazine case 20 pcs		PS2506-4
PS2506L-4	PS2506L-4-A				

*1 For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings		Unit
			PS2506-1, PS2506L-1	PS2506-2,-4 PS2506L-2,-4	
Diode	Forward Current (DC)	I _F	±80		mA/ch
	Power Dissipation Derating	ΔP _D /°C	1.5	1.2	mW/°C
	Power Dissipation	P _D	150	120	mW/ch
	Peak Forward Current ^{*1}	I _{FP}	±1		A/ch
Transistor	Collector to Emitter Voltage	V _{CEO}	40		V
	Emitter to Collector Voltage	V _{ECO}	6		V
	Collector Current	I _C	200	160	mA/ch
	Power Dissipation Derating	ΔP _C /°C	2.0	1.6	mW/°C
	Power Dissipation	P _C	200	160	mW/ch
Isolation Voltage ^{*2}		BV	5 000		Vr.m.s.
Operating Ambient Temperature		T _A	-55 to +100		°C
Storage Temperature		T _{stg}	-55 to +150		°C

*1 PW = 100 μs, Duty Cycle = 1%

*2 AC voltage for 1 minute at T_A = 25°C, RH = 60% between input and output

Pins 1-2 shorted together, 3-4 shorted together (PS2506-1, PS2506L-1).

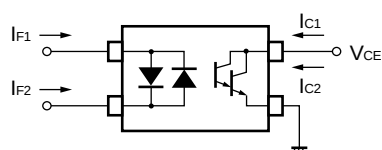
Pins 1-4 shorted together, 5-8 shorted together (PS2506-2, PS2506L-2).

Pins 1-8 shorted together, 9-16 shorted together (PS2506-4, PS2506L-4).

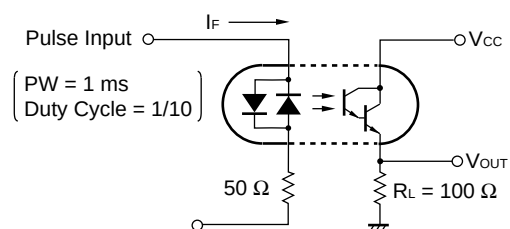
ELECTRICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$)

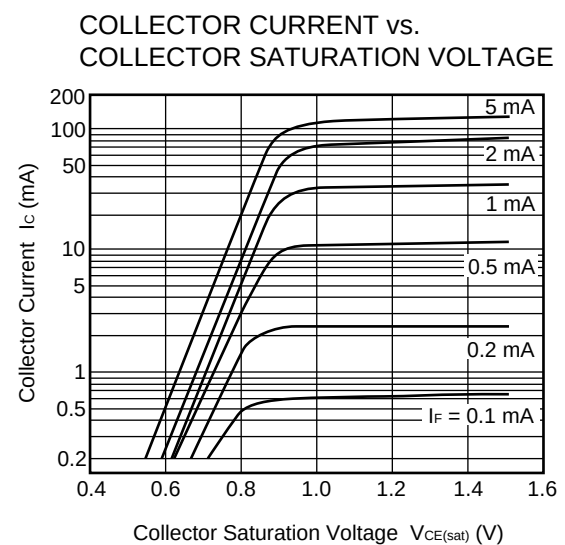
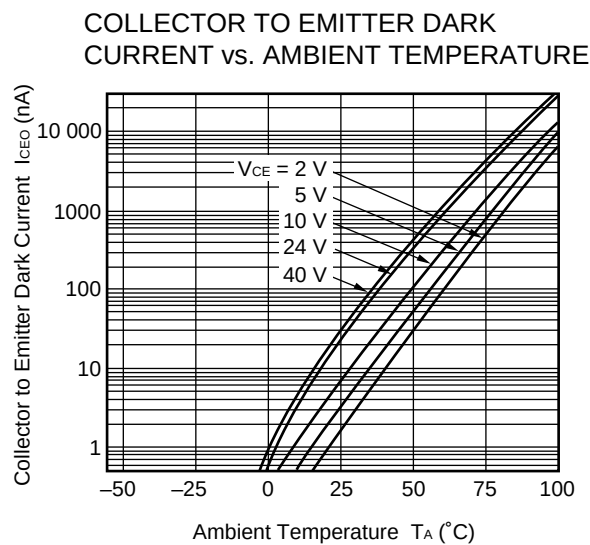
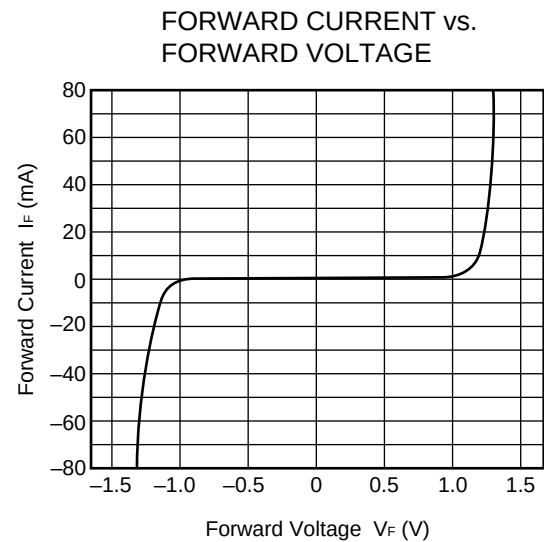
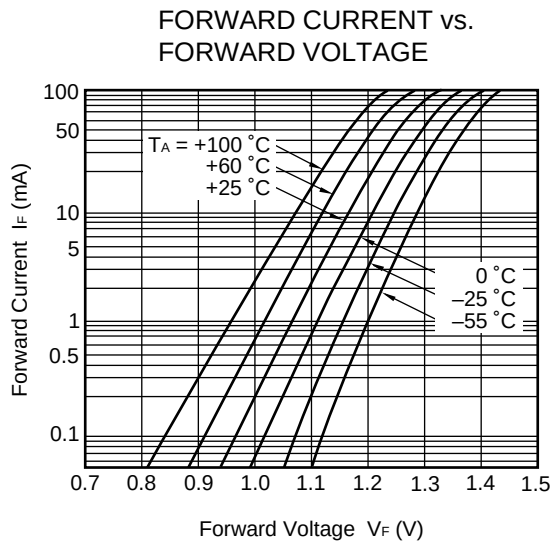
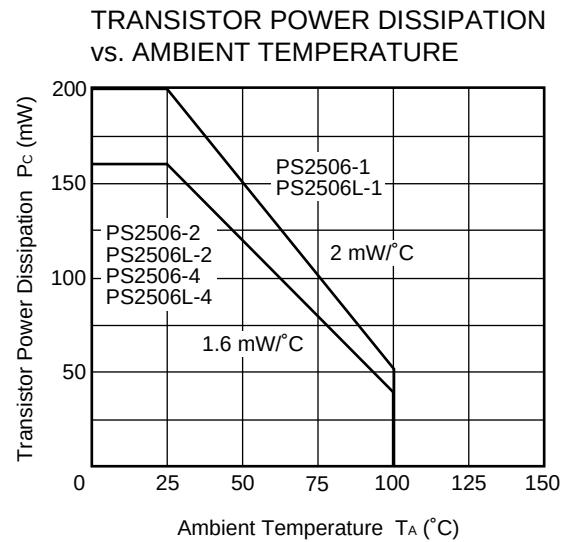
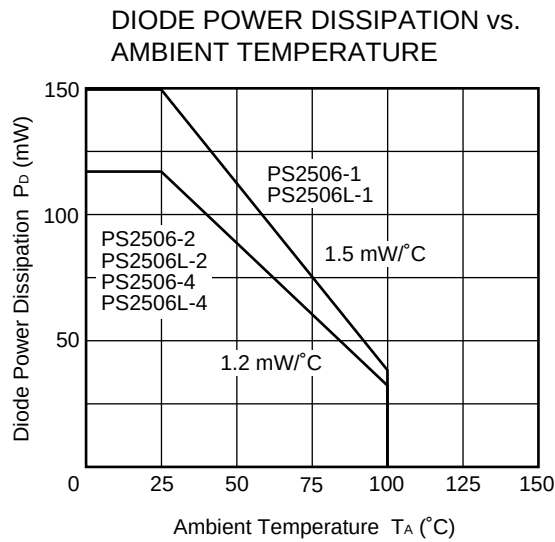
Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V_F	$I_F = \pm 10\text{ mA}$		1.17	1.4	V
	Terminal Capacitance	C_t	$V = 0\text{ V}$, $f = 1.0\text{ MHz}$		100		pF
Transistor	Collector to Emitter Dark Current	I_{CEO}	$V_{CE} = 40\text{ V}$, $I_F = 0\text{ mA}$			400	nA
Coupled	Current Transfer Ratio (I_C/I_F)	CTR	$I_F = \pm 1\text{ mA}$, $V_{CE} = 2\text{ V}$	200	2 000		%
	CTR Ratio ^{*1}	CTR1/ CTR2	$I_F = 1\text{ mA}$, $V_{CE} = 2\text{ V}$	0.3	1.0	3.0	
	Collector Saturation Voltage	$V_{CE(sat)}$	$I_F = \pm 1\text{ mA}$, $I_C = 2\text{ mA}$			1.0	V
	Isolation Resistance	R_{I-O}	$V_{I-O} = 1.0\text{ kV}_{DC}$	10^{11}			Ω
	Isolation Capacitance	C_{I-O}	$V = 0\text{ V}$, $f = 1.0\text{ MHz}$		0.5		pF
	Rise Time ^{*2}	t_r	$V_{CC} = 10\text{ V}$, $I_C = 2\text{ mA}$, $R_L = 100\text{ }\Omega$		100		μs
	Fall Time ^{*2}	t_f			100		

*1 $CTR1 = I_{C1}/I_{F1}$, $CTR2 = I_{C2}/I_{F2}$



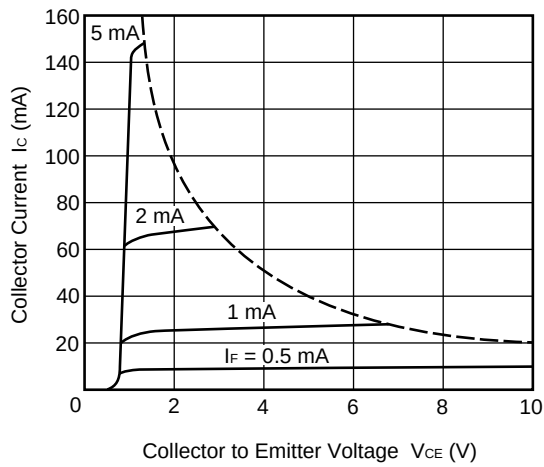
*2 Test circuit for switching time



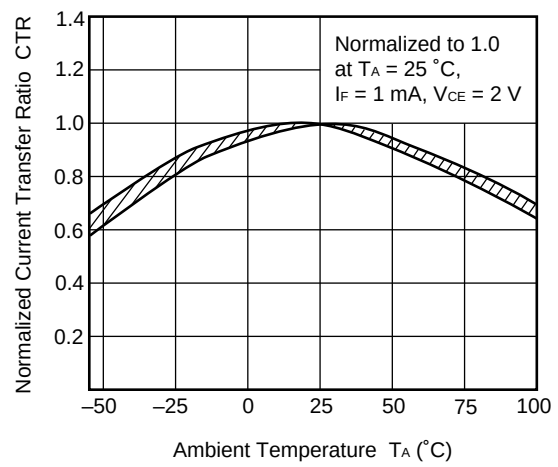
TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise specified)

Remark The graphs indicate nominal characteristics.

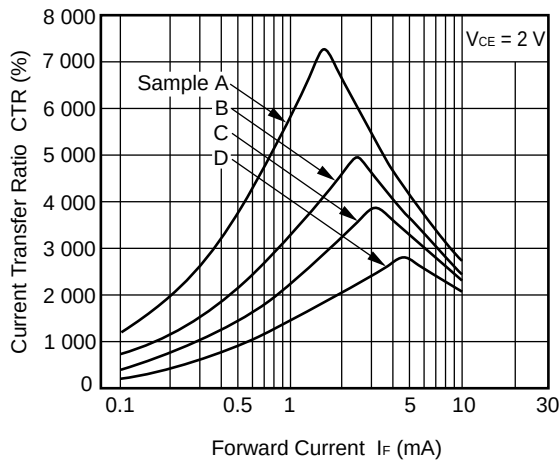
COLLECTOR CURRENT vs.
COLLECTOR TO EMITTER VOLTAGE



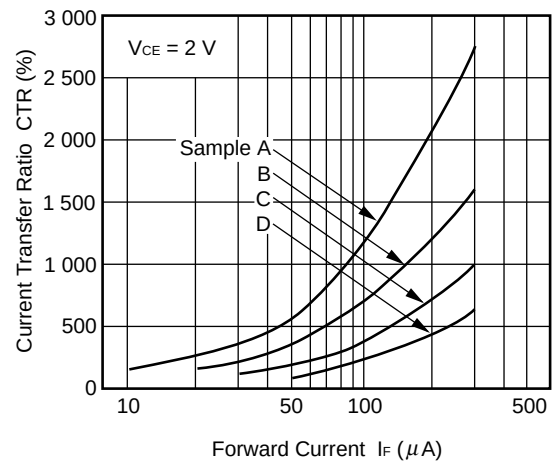
NORMALIZED CURRENT TRANSFER
RATIO vs. AMBIENT TEMPERATURE



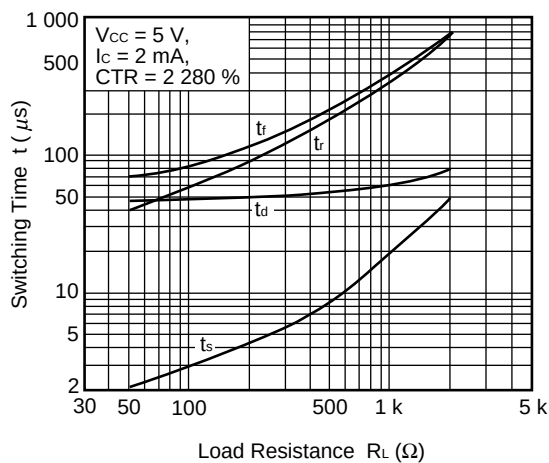
CURRENT TRANSFER RATIO vs.
FORWARD CURRENT



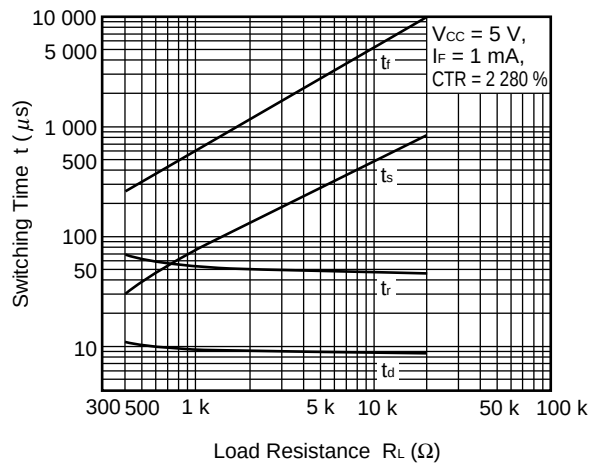
CURRENT TRANSFER RATIO vs.
FORWARD CURRENT



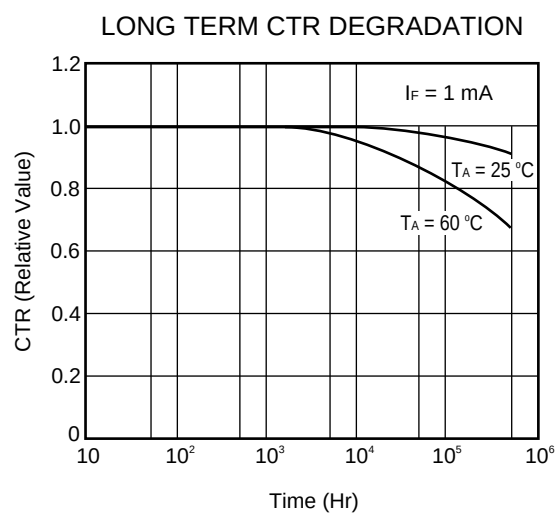
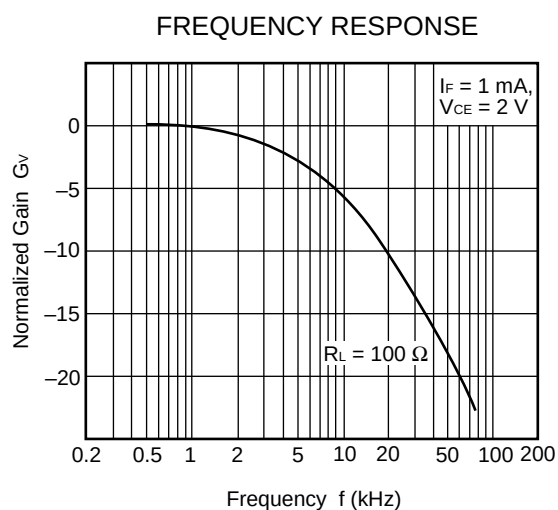
SWITCHING TIME vs.
LOAD RESISTANCE



SWITCHING TIME vs.
LOAD RESISTANCE



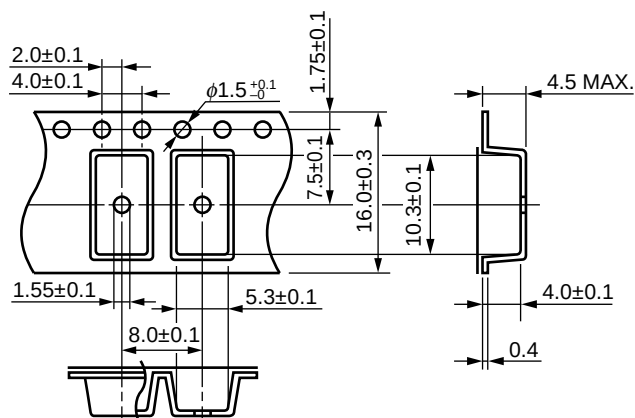
Remark The graphs indicate nominal characteristics.



Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (UNIT : mm)

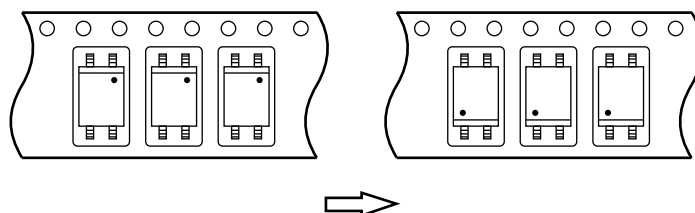
Outline and Dimensions (Tape)



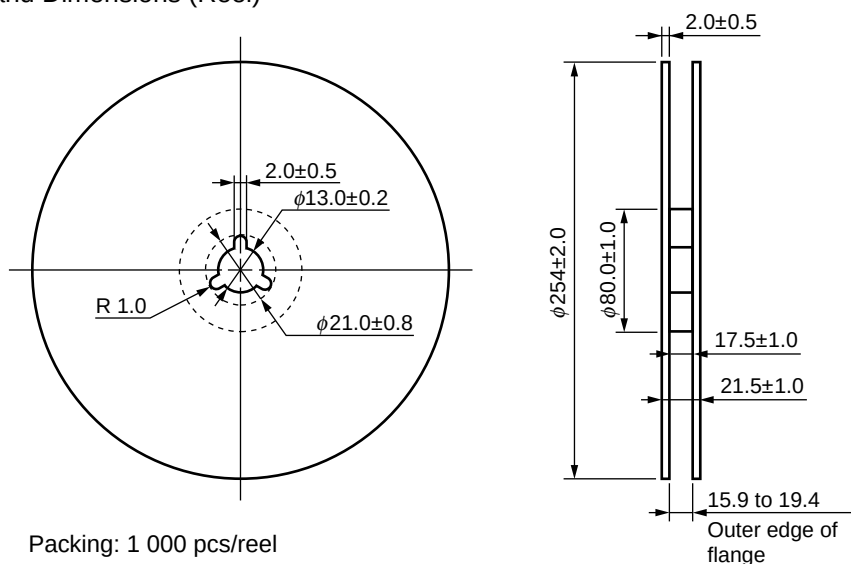
Tape Direction

PS2506L-1-E3

PS2506L-1-E4



Outline and Dimensions (Reel)



Technical drawing of a mechanical part, showing a front view and a side view. The part has a complex shape with two rectangular cutouts and a central circular feature. Dimensions and tolerances are specified in millimeters (mm).

Dimensions and Tolerances:

- Top horizontal dimensions: 2.0 ± 0.1 , 4.0 ± 0.1
- Top right vertical dimension: 1.75 ± 0.1
- Top right circular feature: $\phi 1.5^{+0.1}_0$
- Right side vertical dimensions: 7.5 ± 0.1 , 16.0 ± 0.3 , 10.3 ± 0.1
- Right side horizontal dimension: 4.5 MAX.
- Bottom left horizontal dimensions: 1.55 ± 0.1 , 5.3 ± 0.1
- Bottom center horizontal dimension: 8.0 ± 0.1
- Bottom right horizontal dimensions: 4.0 ± 0.1 , 0.4

Technical drawing of a circular flange with dimensions in millimeters (mm).

Front View (Left):

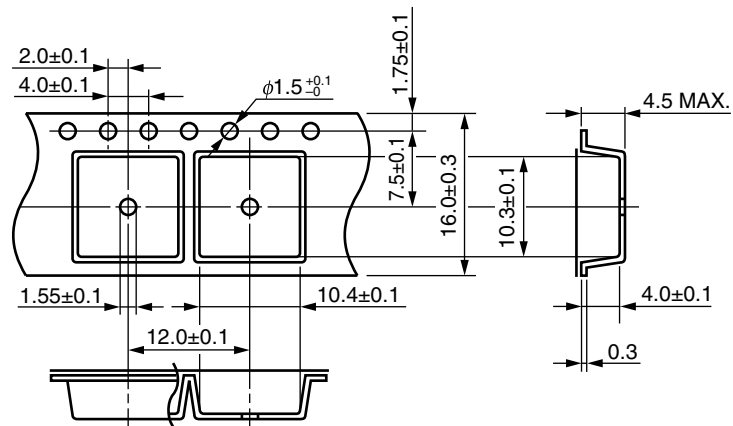
- Outer diameter: $\phi 330 \pm 2.0$
- Inner diameter: $\phi 21.0 \pm 0.8$
- Central hole diameter: $\phi 13.0 \pm 0.2$
- Central raised area radius: $R 1.0$
- Central raised area width: 2.0 ± 0.5

Side View (Right):

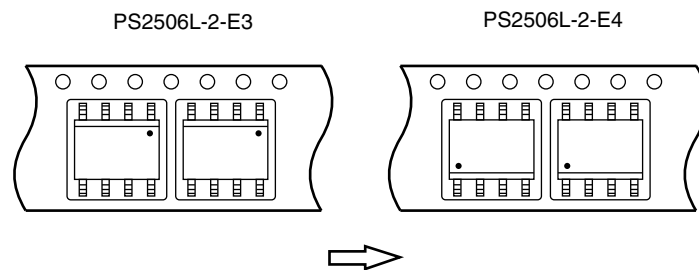
- Total thickness: 2.0 ± 0.5
- Central raised area height: 17.5 ± 1.0
- Flange thickness: 21.5 ± 1.0
- Outer edge of flange: 15.9 to 19.4

Packing: 2 000 pcs/reel

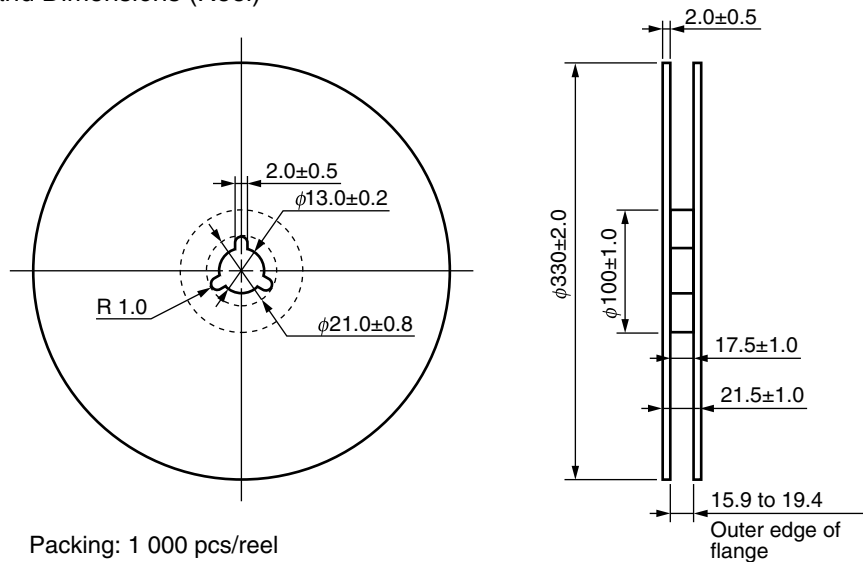
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimensions (Reel)



Packing: 1 000 pcs/reel

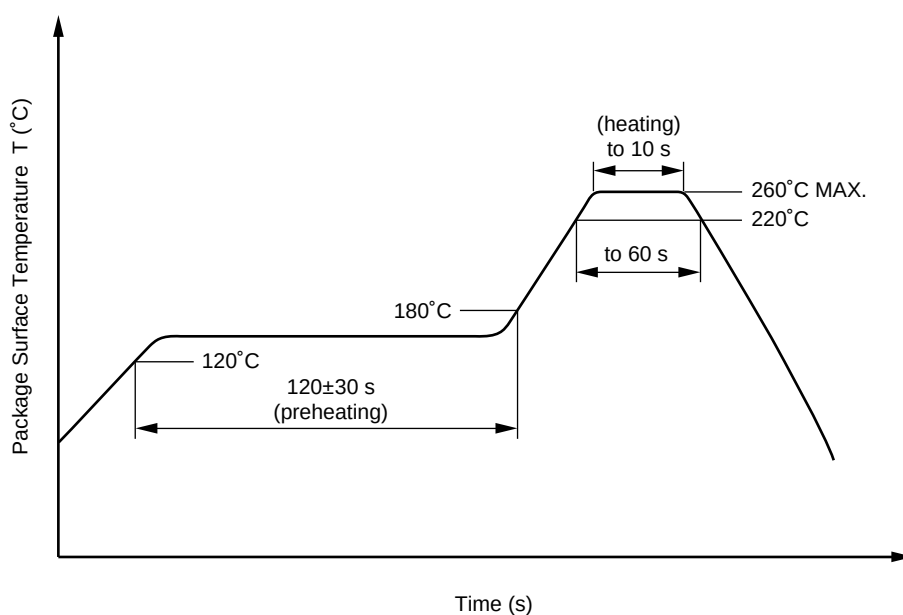
NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

★ (3) Soldering by soldering iron

- Peak temperature (lead part temperature) 350°C or below
- Time (each pins) 3 seconds or less
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

- Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

★ 3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler

Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

USAGE CAUTIONS

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

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 (2) "NEC semiconductor products" means any semiconductor product developed or manufactured by or for NEC (as defined above).

M8E 00.4-0110

Caution	GaAs Products	This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points. • Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below. 1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials. 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal. • Do not burn, destroy, cut, crush, or chemically dissolve the product. • Do not lick the product or in any way allow it to enter the mouth.
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► For further information, please contact

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Subject: Compliance with EU Directives

CEL certifies, to its knowledge, that semiconductor and laser products detailed below are compliant with the requirements of European Union (EU) Directive 2002/95/EC Restriction on Use of Hazardous Substances in electrical and electronic equipment (RoHS) and the requirements of EU Directive 2003/11/EC Restriction on Penta and Octa BDE.

CEL Pb-free products have the same base part number with a suffix added. The suffix –A indicates that the device is Pb-free. The –AZ suffix is used to designate devices containing Pb which are exempted from the requirement of RoHS directive (*). In all cases the devices have Pb-free terminals. All devices with these suffixes meet the requirements of the RoHS directive.

This status is based on CEL's understanding of the EU Directives and knowledge of the materials that go into its products as of the date of disclosure of this information.

Restricted Substance per RoHS	Concentration Limit per RoHS (values are not yet fixed)	Concentration contained in CEL devices	
		-A	-AZ
Lead (Pb)	< 1000 PPM	Not Detected	(*)
Mercury	< 1000 PPM	Not Detected	
Cadmium	< 100 PPM	Not Detected	
Hexavalent Chromium	< 1000 PPM	Not Detected	
PBB	< 1000 PPM	Not Detected	
PBDE	< 1000 PPM	Not Detected	

If you should have any additional questions regarding our devices and compliance to environmental standards, please do not hesitate to contact your local representative.

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